

# MSARW80G20A

## (MX028)

### Features

- Oxide passivated structure for very low leakage currents
- Epitaxial structure minimizes forward voltage drop
- Hermetically sealed, low profile ceramic surface mount power package
- Low package inductance
- Very low thermal resistance
- available with TXV (MSARW80G20AV) or S-level (MSARW80G20AS) screening i.a.w. Microsemi internal procedure PS11.50

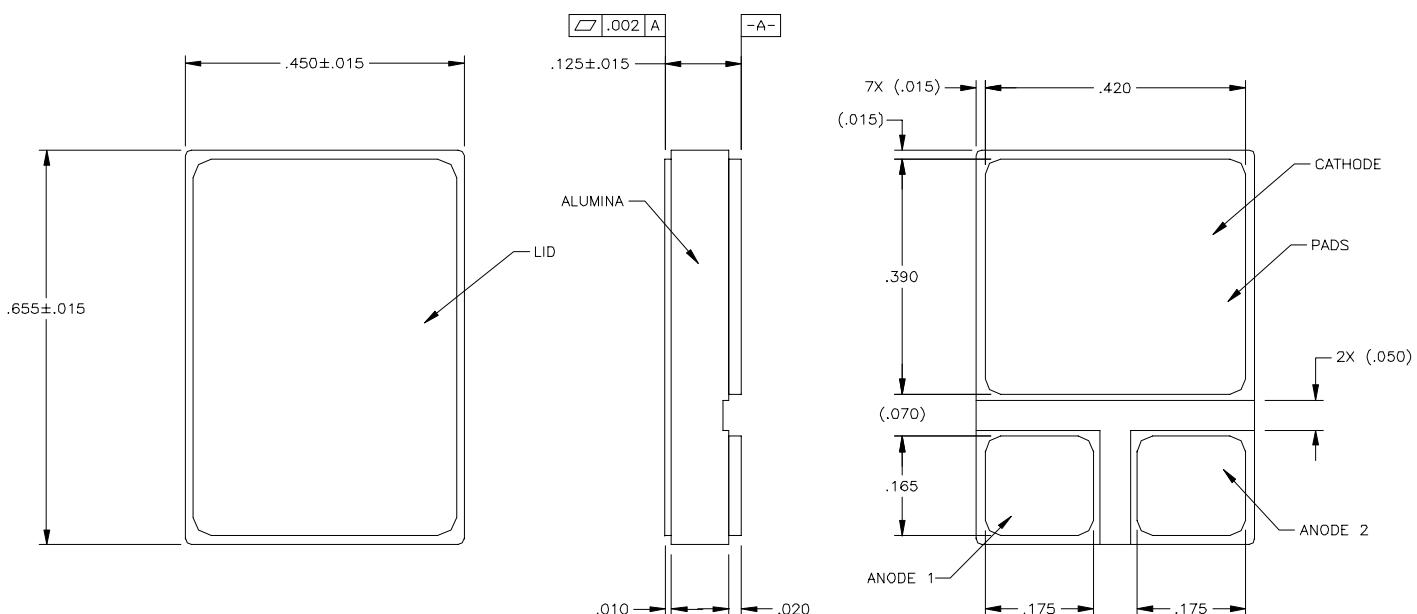
**200 Volts**  
**80 Amps**  
**37 ns**

**ULTRAFAST**  
**RECTIFIER**

### Maximum Ratings @ 25°C (unless otherwise specified)

DESCRIPTION	SYMBOL	MAX.	UNIT
Peak Repetitive Reverse Voltage	$V_{RRM}$	200	Volts
Working Peak Reverse Voltage	$V_{RWM}$	200	Volts
DC Blocking Voltage	$V_R$	200	Volts
Average Rectified Forward Current, $T_c \leq 135^\circ\text{C}$	$I_{F(\text{ave})}$	80	Amps
Nonrepetitive Peak Surge Current, $t_p = 8.3 \text{ ms}$ , half-sinewave	$I_{FSM}$	250	Amps
Junction Temperature Range	$T_j$	-65 to +200	°C
Storage Temperature Range	$T_{stg}$	-65 to +200	°C
Thermal Resistance, Junction to Case	$\theta_{JC}$	0.8 (typ.0.35)	°C/W

### Mechanical Outline



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### Electrical Parameters

DESCRIPTION	SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT
Reverse (Leakage) Current	$IR_{25}$	VR= 200 Vdc, $T_c = 25^\circ C$		-	250	$\mu A$
	$IR_{100}$	VR= 200 Vdc, $T_c = 100^\circ C$		-	10	mA
Forward Voltage pulse test, pw= 300 $\mu s$ $d/c \leq 2\%$	VF1	IF= 5 A, $T_c = 25^\circ C$		720	750	mV
	VF2	IF= 25 A, $T_c = 25^\circ C$		860	900	mV
	VF3	IF= 50 A, $T_c = 25^\circ C$		950	1050	mV
	VF4	IF= 80 A, $T_c = 25^\circ C$		1050		mV
	VF5	IF= 50 A, $T_c = -55^\circ C$			1150	mV
	VF6	IF= 50 A, $T_c = 100^\circ C$		830		mV
Junction Capacitance	Cj1	VR= 10 Vdc			500	pF
Reverse Recovery Time	trr	IF= 9.9A, dIF/dt= 200A/ $\mu s$ , VR= 30V		35	37	ns
Reverse Recovery Current	$I_{RM(rec)}$	IF= 9.9A, dIF/dt= 200A/ $\mu s$ , VR= 30V		5	5.5	A
Breakdown Voltage	BVR	IR= 250 $\mu A$ , $T_c = 25^\circ C$	200			V

